

Advance Product Change Notification

202208027A : S32G2xx Silicon Revision from 0P77B to 1P77B and Qualification of YoungYiel (YY) Lid Supplier

| | Note: This notice is N | e: This notice is NXP Company Proprietary. | | | | | | |
|---|------------------------|--|---------------------------------|----------------------|-----------------------------------|--|--|--|
| Issue Date: Dec 07, 2022 Change Category | | | | | | | | |
| | [] Wafer Fab Process | [] Assembly Process | [] Product Marking | [] Test Process | [] Design | | | |
| | [] Wafer Fab Materials | [X] Assembly Materials | [] Mechanical Specification | [] Test Equipment | [X] Errata | | | |
| | [] Wafer Fab Location | [] Assembly Location | [] Packing/Shipping/Labeling | [] Test Location | [] Electrical spec./Test coverage | | | |
| | [X] Firmware | [X] Other: Reference Manual | | | | | | |

PCN Overview

Description

This Advance Product Change Notification announces the planned silicon revision from maskset 0P77B to 1P77B for the devices associated with this notification.

Security issues are addressed in this silicon revision. Please contact NXP PSIRT (psirt@nxp) for details on silicon revision.

In addition, new silicon revision 1P77B devices will include YoungYiel (YY) as an additional lid supplier. There is no impact to the fit, function, reliability, or quality between current lid and YoungYiel (YY), however, there is a slight visual difference.

To support the transition to the new silicon revision (1P77B), a Discontinuance Notification will be issued (planned issuance March 2023) with new replacement part numbers and qualification results. Qualified samples of the new silicon revision 1P77B are expected in March 2023, with volume production ramp expected in September 2023, dates subject to change.

The new silicon revision (1P77B) will require the use of Integrated Software Bundle 2023.03, or future bundles.

Any orders on the existing part numbers with silicon revision 0P77B that will not be fulfilled will need to be transitioned to the equivalent replacement part number using silicon revision 1P77B.

Please see attached for planned replacement part numbers, part marking, and visual comparison between current and new lid.

Corresponding ZVEI Delta Qualification Matrix ID: SEM-DS-02, SEM-DE-04, SEM-PA-16

Reason

Security issues are addressed in the silicon revision. Qualification of YoungYiel (YY) as a lid supplier for supply assurance.

Identification of Affected Products

Replacement part type created, see Parts Affected list Please see attached file for replacement part numbers that will be included in the planned Discontinuance Notification.

Product Availability

Sample Information

Samples are available from Mar 31, 2023 Prototype samples are available upon request. Qualified samples are available from March 31, 2023 **Production** Planned first shipment Sep 29, 2023

Anticipated Impact on Form, Fit, Function, Reliability or Quality

There is no impact to the fit, function, reliability, or quality between current lid and YoungYiel (YY), however, there is a slight visual difference.

There is no impact to the form, fit, function, reliability, or quality for the planned silicon revision from maskset 0P77B to 1P77B.

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

The Self Qualification Report will be ready on Mar 31, 2023. The Final PCN is planned to be issued on: Mar 31, 2023. In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Jan 06, 2023.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Position Change Management

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S32G2XX SILICON REVISION FROM 0P77B TO 1P77B AND QUALIFICATION OF YOUNGYIEL (YY) LID SUPPLIER APCN: 202208027A

Amanda Shearer 29-NOV-2022



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NEW ORDERABLE PART NUMBERS

- As described in the Advance Product Change Notification, new orderable part numbers will be available to replace existing orderable part numbers.
- Replacement part numbers are captured below and will be listed as replacement part numbers in the planned Discontinuance Notice.
- Change in the orderable part number (i.e., "K0" will be replaced by "K1").

| | | New Replacement Part Number | urrent Part Number |
|--------------------------|-------------------------------|-----------------------------|--------------------|
| placed by "V" Temperatur | ote: "C" Temperature (TA) ran | S32G274AABK1VUCR | S32G274AABK0CUCR |
| placed by "V" Temperatur | ote: "C" Temperature (TA) ran | S32G274AABK1VUCT | S32G274AABK0CUCT |
| | | S32G233AABK1VUCR | S32G233AABK0VUCR |
| | | S32G233AABK1VUCT | S32G233AABK0VUCT |
| | | S32G233ASBK1VUCR | S32G233ASBK0VUCR |
| | | S32G233ASBK1VUCT | S32G233ASBK0VUCT |
| | | S32G234MABK1VUCR | S32G234MABK0VUCR |
| | | S32G234MABK1VUCT | S32G234MABK0VUCT |
| | | S32G234MSBK1VUCR | S32G234MSBK0VUCR |
| | | S32G234MSBK1VUCT | S32G234MSBK0VUCT |
| | | S32G254AABK1VUCR | S32G254AABK0VUCR |
| | | S32G254AABK1VUCT | S32G254AABK0VUCT |
| | | S32G254ASBK1VUCR | S32G254ASBK0VUCR |
| | | S32G254ASBK1VUCT | S32G254ASBK0VUCT |
| | | S32G274AABK1VUCR | S32G274AABK0VUCR |
| | | S32G274AABK1VUCT | S32G274AABK0VUCT |
| | | S32G274ASBK1VUCR | S32G274ASBK0VUCR |
| | | S32G274ASBK1VUCT | S32G274ASBK0VUCT |
| ERNAL USE 2 | | | |

REPRESENTATIVE PART MARKING

Mask set revision is included on part marking "MMMMM"

- Current Mask set revision: 0N77P
- New Mask set revision: 1N77P

!* ! ! ! ! ! (N) ! ! S32G274AABVUC! ! MMMMM ! ! AWLYYWWZ ! ! !

LID VISUAL COMPARISON

| | Current | New: YoungYiel (YY) | |
|--------|---------|---------------------|---|
| Тор | | | Identical size and shape YY lid slightly more polished |
| Bottom | | | Identical size and shape YY lid slightly more polished |
| Side | | | Identical widthYY lid slightly more polished |
| Side | | | YY lid shows tooling mark |



SECURE CONNECTIONS FOR A SMARTER WORLD

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